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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Active
Number of LABs/CLBs	6036
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	203
Number of Gates	108000
Voltage - Supply	2.25V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	256-LBGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a54sx72a-fgg256i

Temperature Grade Offering

Package	A54SX08A	A54SX16A	A54SX32A	A54SX72A
PQ208	C,I,A,M	C,I,A,M	C,I,A,M	C,I,A,M
TQ100	C,I,A,M	C,I,A,M	C,I,A,M	
TQ144	C,I,A,M	C,I,A,M	C,I,A,M	
TQ176			C,I,M	
BG329			C,I,M	
FG144	C,I,A,M	C,I,A,M	C,I,A,M	
FG256		C,I,A,M	C,I,A,M	C,I,A,M
FG484			C,I,M	C,I,A,M
CQ208			C,M,B	C,M,B
CQ256			C,M,B	C,M,B

Notes:

1. C = Commercial
2. I = Industrial
3. A = Automotive
4. M = Military
5. B = MIL-STD-883 Class B
6. For more information regarding automotive products, refer to the SX-A Automotive Family FPGAs datasheet.
7. For more information regarding Mil-Temp and ceramic packages, refer to the HiRel SX-A Family FPGAs datasheet.

Speed Grade and Temperature Grade Matrix

	F	Std	-1	-2	-3
Commercial	✓	✓	✓	✓	Discontinued
Industrial		✓	✓	✓	Discontinued
Automotive		✓			
Military		✓	✓		
MIL-STD-883B		✓	✓		

Notes:

1. For more information regarding automotive products, refer to the SX-A Automotive Family FPGAs datasheet.
2. For more information regarding Mil-Temp and ceramic packages, refer to the HiRel SX-A Family FPGAs datasheet.

Contact your Actel Sales representative for more information on availability.

Detailed Specifications

Operating Conditions

Table 2-1 • Absolute Maximum Ratings

Symbol	Parameter	Limits	Units
V_{CCI}	DC Supply Voltage for I/Os	-0.3 to +6.0	V
V_{CCA}	DC Supply Voltage for Arrays	-0.3 to +3.0	V
V_I	Input Voltage	-0.5 to +5.75	V
V_O	Output Voltage	-0.5 to + V_{CCI} + 0.5	V
T_{STG}	Storage Temperature	-65 to +150	°C

Note: *Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum rated conditions for extended periods may affect device reliability. Devices should not be operated outside the "Recommended Operating Conditions".

Table 2-2 • Recommended Operating Conditions

Parameter	Commercial	Industrial	Units
Temperature Range	0 to +70	-40 to +85	°C
2.5 V Power Supply Range (V_{CCA} and V_{CCI})	2.25 to 2.75	2.25 to 2.75	V
3.3 V Power Supply Range (V_{CCI})	3.0 to 3.6	3.0 to 3.6	V
5 V Power Supply Range (V_{CCI})	4.75 to 5.25	4.75 to 5.25	V

Typical SX-A Standby Current

Table 2-3 • Typical Standby Current for SX-A at 25°C with $V_{CCA} = 2.5$ V

Product	$V_{CCI} = 2.5$ V	$V_{CCI} = 3.3$ V	$V_{CCI} = 5$ V
A54SX08A	0.8 mA	1.0 mA	2.9 mA
A54SX16A	0.8 mA	1.0 mA	2.9 mA
A54SX32A	0.9 mA	1.0 mA	3.0 mA
A54SX72A	3.6 mA	3.8 mA	4.5 mA

Table 2-4 • Supply Voltages

V_{CCA}	V_{CCI}^*	Maximum Input Tolerance	Maximum Output Drive
2.5 V	2.5 V	5.75 V	2.7 V
2.5 V	3.3 V	5.75 V	3.6 V
2.5 V	5 V	5.75 V	5.25 V

Note: *3.3 V PCI is not 5 V tolerant due to the clamp diode, but instead is 3.3 V tolerant.

Electrical Specifications

Table 2-5 • 3.3 V LVTTL and 5 V TTL Electrical Specifications

Symbol	Parameter	Commercial		Industrial		Units	
		Min.	Max.	Min.	Max.		
V_{OH}	$V_{CCI} = \text{Minimum}$ $V_I = V_{IH} \text{ or } V_{IL}$	($I_{OH} = -1 \text{ mA}$)	0.9 V_{CCI}	0.9 V_{CCI}		V	
	$V_{CCI} = \text{Minimum}$ $V_I = V_{IH} \text{ or } V_{IL}$	($I_{OH} = -8 \text{ mA}$)	2.4	2.4		V	
V_{OL}	$V_{CCI} = \text{Minimum}$ $V_I = V_{IH} \text{ or } V_{IL}$	($I_{OL} = 1 \text{ mA}$)	0.4	0.4		V	
	$V_{CCI} = \text{Minimum}$ $V_I = V_{IH} \text{ or } V_{IL}$	($I_{OL} = 12 \text{ mA}$)	0.4	0.4		V	
V_{IL}	Input Low Voltage		0.8	0.8		V	
V_{IH}	Input High Voltage		2.0	5.75	2.0	5.75	V
I_{IL}/I_{IH}	Input Leakage Current, $V_{IN} = V_{CCI} \text{ or GND}$		-10	10	-10	10	μA
I_{OZ}	Tristate Output Leakage Current		-10	10	-10	10	μA
t_R, t_F	Input Transition Time t_R, t_F		10	10		ns	
C_{IO}	I/O Capacitance		10	10		pF	
I_{CC}	Standby Current		10	20		mA	
IV Curve*	Can be derived from the IBIS model on the web.						

Note: *The IBIS model can be found at <http://www.actel.com/download/ibis/default.aspx>.

Table 2-6 • 2.5 V LVCMS2 Electrical Specifications

Symbol	Parameter	Commercial		Industrial		Units	
		Min.	Max.	Min.	Max.		
V_{OH}	$V_{DD} = \text{MIN},$ $V_I = V_{IH} \text{ or } V_{IL}$	($I_{OH} = -100 \mu\text{A}$)	2.1	2.1		V	
	$V_{DD} = \text{MIN},$ $V_I = V_{IH} \text{ or } V_{IL}$	($I_{OH} = -1 \text{ mA}$)	2.0	2.0		V	
	$V_{DD} = \text{MIN},$ $V_I = V_{IH} \text{ or } V_{IL}$	($I_{OH} = -2 \text{ mA}$)	1.7	1.7		V	
V_{OL}	$V_{DD} = \text{MIN},$ $V_I = V_{IH} \text{ or } V_{IL}$	($I_{OL} = 100 \mu\text{A}$)	0.2	0.2		V	
	$V_{DD} = \text{MIN},$ $V_I = V_{IH} \text{ or } V_{IL}$	($I_{OL} = 1 \text{ mA}$)	0.4	0.4		V	
	$V_{DD} = \text{MIN},$ $V_I = V_{IH} \text{ or } V_{IL}$	($I_{OL} = 2 \text{ mA}$)	0.7	0.7		V	
V_{IL}	Input Low Voltage, $V_{OUT} \leq V_{VOL(\text{max})}$		-0.3	0.7	-0.3	0.7	V
V_{IH}	Input High Voltage, $V_{OUT} \geq V_{VOH(\text{min})}$		1.7	5.75	1.7	5.75	V
I_{IL}/I_{IH}	Input Leakage Current, $V_{IN} = V_{CCI} \text{ or GND}$		-10	10	-10	10	μA
I_{OZ}	Tristate Output Leakage Current, $V_{OUT} = V_{CCI} \text{ or GND}$		-10	10	-10	10	μA
t_R, t_F	Input Transition Time t_R, t_F		10	10		ns	
C_{IO}	I/O Capacitance		10	10		pF	
I_{CC}	Standby Current		10	20		mA	
IV Curve*	Can be derived from the IBIS model on the web.						

Note: *The IBIS model can be found at <http://www.actel.com/download/ibis/default.aspx>.

Figure 2-1 shows the 5 V PCI V/I curve and the minimum and maximum PCI drive characteristics of the SX-A family.

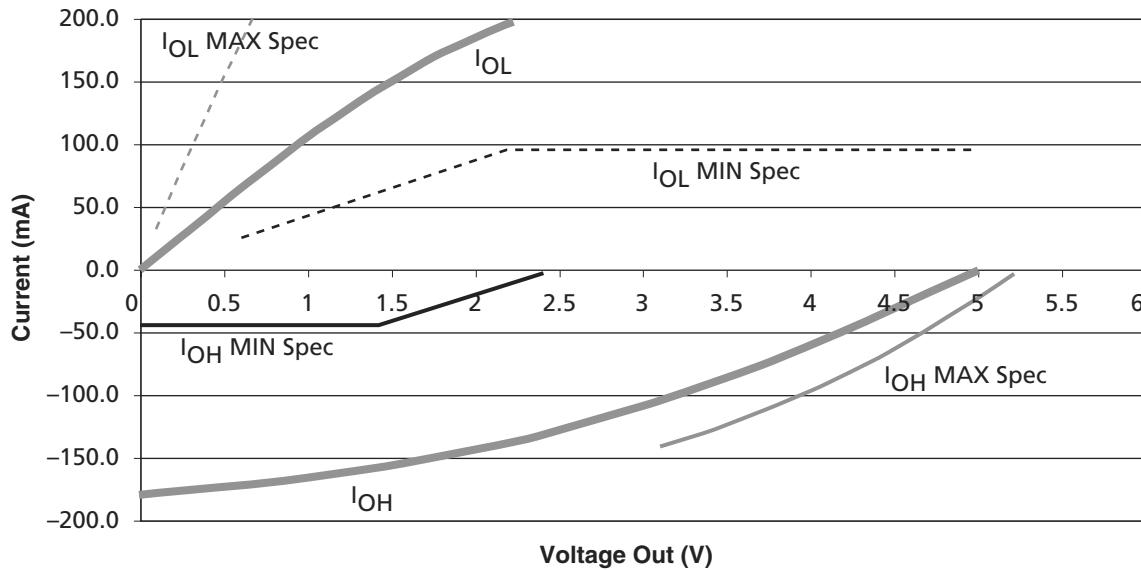


Figure 2-1 • 5 V PCI V/I Curve for SX-A Family

$$I_{OH} = 11.9 * (V_{OUT} - 5.25) * (V_{OUT} + 2.45)$$

for $V_{CCI} > V_{OUT} > 3.1V$

EQ 2-1

$$I_{OL} = 78.5 * V_{OUT} * (4.4 - V_{OUT})$$

for $0V < V_{OUT} < 0.71V$

EQ 2-2

Table 2-9 • DC Specifications (3.3 V PCI Operation)

Symbol	Parameter	Condition	Min.	Max.	Units
V_{CCA}	Supply Voltage for Array		2.25	2.75	V
V_{CCI}	Supply Voltage for I/Os		3.0	3.6	V
V_{IH}	Input High Voltage		$0.5V_{CCI}$	$V_{CCI} + 0.5$	V
V_{IL}	Input Low Voltage		-0.5	$0.3V_{CCI}$	V
I_{IPU}	Input Pull-up Voltage ¹		$0.7V_{CCI}$	-	V
I_{IL}	Input Leakage Current ²	$0 < V_{IN} < V_{CCI}$	-10	+10	μA
V_{OH}	Output High Voltage	$I_{OUT} = -500 \mu A$	$0.9V_{CCI}$	-	V
V_{OL}	Output Low Voltage	$I_{OUT} = 1,500 \mu A$		$0.1V_{CCI}$	V
C_{IN}	Input Pin Capacitance ³		-	10	pF
C_{CLK}	CLK Pin Capacitance		5	12	pF

Notes:

1. This specification should be guaranteed by design. It is the minimum voltage to which pull-up resistors are calculated to pull a floated network. Designers should ensure that the input buffer is conducting minimum current at this input voltage in applications sensitive to static power utilization.
2. Input leakage currents include hi-Z output leakage for all bidirectional buffers with tristate outputs.
3. Absolute maximum pin capacitance for a PCI input is 10 pF (except for CLK).

Table 2-17 • A54SX08A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 4.75\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-2 Speed		-1 Speed		Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Dedicated (Hardwired) Array Clock Networks								
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.2		1.3		1.5		2.3 ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)		1.0		1.2		1.4 2.0 ns	
t_{HPWH}	Minimum Pulse Width High	1.6		1.8		2.1		2.9 ns
t_{HPWL}	Minimum Pulse Width Low	1.6		1.8		2.1		2.9 ns
t_{HCKSW}	Maximum Skew		0.4		0.4		0.5 0.8 ns	
t_{HP}	Minimum Period	3.2		3.6		4.2		5.8 ns
f_{HMAX}	Maximum Frequency		313		278		238 172 MHz	
Routed Array Clock Networks								
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	0.9		1.0		1.2		1.7 ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)		1.5		1.7		2.0 2.7 ns	
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	0.9		1.0		1.2		1.7 ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	1.5		1.7		2.0		2.7 ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	1.1		1.3		1.5		2.1 ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	1.6		1.8		2.1		2.9 ns
t_{RPWH}	Minimum Pulse Width High	1.6		1.8		2.1		2.9 ns
t_{RPWL}	Minimum Pulse Width Low	1.6		1.8		2.1		2.9 ns
t_{RCKSW}	Maximum Skew (Light Load)		0.8		0.9		1.1 1.5 ns	
t_{RCKSW}	Maximum Skew (50% Load)	0.8		1.0		1.1		1.5 ns
t_{RCKSW}	Maximum Skew (100% Load)	0.9		1.0		1.2		1.7 ns

Table 2-19 • A54SX08A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-2 Speed		-1 Speed		Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	Max.	
3.3 V PCI Output Module Timing¹								
t_{DLH}	Data-to-Pad Low to High	2.2	2.4	2.9	4.0	ns		
t_{DHL}	Data-to-Pad High to Low	2.3	2.6	3.1	4.3	ns		
t_{ENZL}	Enable-to-Pad, Z to L	1.7	1.9	2.2	3.1	ns		
t_{ENZH}	Enable-to-Pad, Z to H	2.2	2.4	2.9	4.0	ns		
t_{ENLZ}	Enable-to-Pad, L to Z	2.8	3.2	3.8	5.3	ns		
t_{ENHZ}	Enable-to-Pad, H to Z	2.3	2.6	3.1	4.3	ns		
d_{TLH}^2	Delta Low to High	0.03	0.03	0.04	0.045	ns/pF		
d_{THL}^2	Delta High to Low	0.015	0.015	0.015	0.025	ns/pF		
3.3 V LVTTL Output Module Timing³								
t_{DLH}	Data-to-Pad Low to High	3.0	3.4	4.0	5.6	ns		
t_{DHL}	Data-to-Pad High to Low	3.0	3.3	3.9	5.5	ns		
t_{DHLS}	Data-to-Pad High to Low—low slew	10.4	11.8	13.8	19.3	ns		
t_{ENZL}	Enable-to-Pad, Z to L	2.6	2.9	3.4	4.8	ns		
t_{ENZLS}	Enable-to-Pad, Z to L—low slew	18.9	21.3	25.4	34.9	ns		
t_{ENZH}	Enable-to-Pad, Z to H	3	3.4	4	5.6	ns		
t_{ENLZ}	Enable-to-Pad, L to Z	3.3	3.7	4.4	6.2	ns		
t_{ENHZ}	Enable-to-Pad, H to Z	3	3.3	3.9	5.5	ns		
d_{TLH}^2	Delta Low to High	0.03	0.03	0.04	0.045	ns/pF		
d_{THL}^2	Delta High to Low	0.015	0.015	0.015	0.025	ns/pF		
d_{THLS}^2	Delta High to Low—low slew	0.053	0.067	0.073	0.107	ns/pF		

Notes:

1. Delays based on 10 pF loading and 25 Ω resistance.
2. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[|LH|HL|HLS]})$$
 where C_{load} is the load capacitance driven by the I/O in pF
 $d_{T[|LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.
3. Delays based on 35 pF loading.

Table 2-21 • A54SX16A Timing Characteristics (Continued)
 (Worst-Case Commercial Conditions, $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
t_{INYH}	Input Data Pad to Y High 5 V PCI	0.5	0.5	0.6	0.7	0.9	ns
t_{INYL}	Input Data Pad to Y Low 5 V PCI	0.7	0.8	0.9	1.1	1.5	ns
t_{IYH}	Input Data Pad to Y High 5 V TTL	0.5	0.5	0.6	0.7	0.9	ns
t_{IYL}	Input Data Pad to Y Low 5 V TTL	0.7	0.8	0.9	1.1	1.5	ns
Input Module Predicted Routing Delays²							
t_{IRD1}	FO = 1 Routing Delay	0.3	0.3	0.3	0.4	0.6	ns
t_{IRD2}	FO = 2 Routing Delay	0.4	0.5	0.5	0.6	0.8	ns
t_{IRD3}	FO = 3 Routing Delay	0.5	0.6	0.7	0.8	1.1	ns
t_{IRD4}	FO = 4 Routing Delay	0.7	0.8	0.9	1.0	1.4	ns
t_{IRD8}	FO = 8 Routing Delay	1.2	1.4	1.5	0.8	2.5	ns
t_{IRD12}	FO = 12 Routing Delay	1.7	2.0	2.2	2.6	3.6	ns

Notes:

1. All -3 speed grades have been discontinued.
2. For dual-module macros, use $t_{PD} + t_{RD1} + t_{PDn}$, $t_{RCO} + t_{RD1} + t_{PDn}$, or $t_{PD1} + t_{RD1} + t_{SUD}$, whichever is appropriate.
3. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual performance.

Table 2-22 • A54SX16A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 2.25\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.2	1.4	1.6	1.8	2.8	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.0	1.1	1.2	1.5	2.2	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.7	1.9	2.2	3.0	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.7	1.9	2.2	3.0	ns
t_{HCKSW}	Maximum Skew	0.3	0.3	0.4	0.4	0.7	ns
t_{HP}	Minimum Period	2.8	3.4	3.8	4.4	6.0	ns
f_{HMAX}	Maximum Frequency	357	294	263	227	167	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	1.0	1.2	1.3	1.6	2.2	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	1.3	1.5	1.7	2.0	2.8	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	1.3	1.5	1.7	2.0	2.8	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.7	1.9	2.2	3.0	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.7	1.9	2.2	3.0	ns
t_{RCKSW}	Maximum Skew (Light Load)	0.8	0.9	1.0	1.2	1.7	ns
t_{RCKSW}	Maximum Skew (50% Load)	0.8	0.9	1.0	1.2	1.7	ns
t_{RCKSW}	Maximum Skew (100% Load)	1.0	1.1	1.3	1.5	2.1	ns

Note: *All -3 speed grades have been discontinued.

Table 2-23 • A54SX16A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.2	1.4	1.6	1.8	2.8	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.0	1.1	1.3	1.5	2.2	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.7	1.9	2.2	3.0	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.7	1.9	2.2	3.0	ns
t_{HCKSW}	Maximum Skew	0.3	0.3	0.4	0.4	0.6	ns
t_{HP}	Minimum Period	2.8	3.4	3.8	4.4	6.0	ns
f_{HMAX}	Maximum Frequency	357	294	263	227	167	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	1.0	1.2	1.3	1.5	2.1	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	1.1	1.3	1.4	1.7	2.3	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	1.1	1.3	1.5	1.7	2.4	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	1.3	1.5	1.7	2.0	2.7	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	1.3	1.5	1.7	2.0	2.8	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.7	1.9	2.2	3.0	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.7	1.9	2.2	3.0	ns
t_{RCKSW}	Maximum Skew (Light Load)	0.8	0.9	1.0	1.2	1.7	ns
t_{RCKSW}	Maximum Skew (50% Load)	0.8	0.9	1.0	1.2	1.7	ns
t_{RCKSW}	Maximum Skew (100% Load)	1.0	1.1	1.3	1.5	2.1	ns

Note: *All -3 speed grades have been discontinued.

Table 2-25 • A54SX16A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 2.25\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min. Max.	Min. Max.	Min. Max.	Min. Max.	Min. Max.	
2.5 V LVC MOS Output Module Timing^{2, 3}							
t_{DLH}	Data-to-Pad Low to High	3.4	3.9	4.5	5.2	7.3	ns
t_{DHL}	Data-to-Pad High to Low	2.6	3.0	3.3	3.9	5.5	ns
t_{DHLS}	Data-to-Pad High to Low—low slew	11.6	13.4	15.2	17.9	25.0	ns
t_{ENZL}	Enable-to-Pad, Z to L	2.4	2.8	3.2	3.7	5.2	ns
t_{ENZLS}	Data-to-Pad, Z to L—low slew	11.8	13.7	15.5	18.2	25.5	ns
t_{ENZH}	Enable-to-Pad, Z to H	3.4	3.9	4.5	5.2	7.3	ns
t_{ENLZ}	Enable-to-Pad, L to Z	2.1	2.5	2.8	3.3	4.7	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.6	3.0	3.3	3.9	5.5	ns
d_{TLH}^4	Delta Low to High	0.031	0.037	0.043	0.051	0.071	ns/pF
d_{THL}^4	Delta High to Low	0.017	0.017	0.023	0.023	0.037	ns/pF
d_{THLS}^4	Delta High to Low—low slew	0.057	0.06	0.071	0.086	0.117	ns/pF

Note:

1. All -3 speed grades have been discontinued.
2. Delays based on 35 pF loading.
3. The equivalent IO Attribute settings for 2.5 V LVC MOS is 2.5 V LVTTL in the software.
4. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[LH|HL|HLS]})$$
 where C_{load} is the load capacitance driven by the I/O in pF
 $d_{T[LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.

Table 2-26 • A54SX16A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
3.3 V PCI Output Module Timing²							
t_{DLH}	Data-to-Pad Low to High	2.0	2.3	2.6	3.1	4.3	ns
t_{DHL}	Data-to-Pad High to Low	2.2	2.5	2.8	3.3	4.6	ns
t_{ENZL}	Enable-to-Pad, Z to L	1.4	1.7	1.9	2.2	3.1	ns
t_{ENZH}	Enable-to-Pad, Z to H	2.0	2.3	2.6	3.1	4.3	ns
t_{ENLZ}	Enable-to-Pad, L to Z	2.5	2.8	3.2	3.8	5.3	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.2	2.5	2.8	3.3	4.6	ns
d_{TLH}^3	Delta Low to High	0.025	0.03	0.03	0.04	0.045	ns/pF
d_{THL}^3	Delta High to Low	0.015	0.015	0.015	0.015	0.025	ns/pF
3.3 V LVTTL Output Module Timing⁴							
t_{DLH}	Data-to-Pad Low to High	2.8	3.2	3.6	4.3	6.0	ns
t_{DHL}	Data-to-Pad High to Low	2.7	3.1	3.5	4.1	5.7	ns
t_{DHLS}	Data-to-Pad High to Low—low slew	9.5	10.9	12.4	14.6	20.4	ns
t_{ENZL}	Enable-to-Pad, Z to L	2.2	2.6	2.9	3.4	4.8	ns
t_{ENZLS}	Enable-to-Pad, Z to L—low slew	15.8	18.9	21.3	25.4	34.9	ns
t_{ENZH}	Enable-to-Pad, Z to H	2.8	3.2	3.6	4.3	6.0	ns
t_{ENLZ}	Enable-to-Pad, L to Z	2.9	3.3	3.7	4.4	6.2	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.7	3.1	3.5	4.1	5.7	ns
d_{TLH}^3	Delta Low to High	0.025	0.03	0.03	0.04	0.045	ns/pF
d_{THL}^3	Delta High to Low	0.015	0.015	0.015	0.015	0.025	ns/pF
d_{THLS}^3	Delta High to Low—low slew	0.053	0.053	0.067	0.073	0.107	ns/pF

Notes:

1. All -3 speed grades have been discontinued.
2. Delays based on 10 pF loading and 25 Ω resistance.
3. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[LH|HL|HLS]})$$

where C_{load} is the load capacitance driven by the I/O in pF.
 $d_{T[LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.
4. Delays based on 35 pF loading.

Table 2-29 • A54SX32A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 2.25\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.7	2.0	2.2	2.6	4.0	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.7	2.0	2.2	2.6	4.0	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{HCKSW}	Maximum Skew	0.6	0.6	0.7	0.8	1.3	ns
t_{HP}	Minimum Period	2.8	3.2	3.6	4.2	5.8	ns
f_{HMAX}	Maximum Frequency	357	313	278	238	172	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	2.2	2.5	2.9	3.4	4.7	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	2.1	2.4	2.7	3.2	4.4	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	2.4	2.7	3.1	3.6	5.1	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	2.2	2.5	2.8	3.3	4.6	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	2.5	2.9	3.2	3.8	5.3	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	2.4	2.7	3.1	3.6	5.0	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{RCKSW}	Maximum Skew (Light Load)	1.0	1.1	1.3	1.5	2.1	ns
t_{RCKSW}	Maximum Skew (50% Load)	0.9	1.0	1.2	1.4	1.9	ns
t_{RCKSW}	Maximum Skew (100% Load)	0.9	1.0	1.2	1.4	1.9	ns

Note: *All -3 speed grades have been discontinued.

Table 2-30 • A54SX32A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.7	2.0	2.2	2.6	4.0	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.7	2.0	2.2	2.6	4.0	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{HCKSW}	Maximum Skew	0.6	0.6	0.7	0.8	1.3	ns
t_{HP}	Minimum Period	2.8	3.2	3.6	4.2	5.8	ns
f_{HMAX}	Maximum Frequency	357	313	278	238	172	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	2.2	2.5	2.8	3.3	4.6	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	2.1	2.4	2.7	3.2	4.5	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	2.3	2.7	3.1	3.6	5	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	2.2	2.5	2.9	3.4	4.7	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	2.4	2.8	3.2	3.7	5.2	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	2.4	2.8	3.1	3.7	5.1	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{RCKSW}	Maximum Skew (Light Load)	1.0	1.1	1.3	1.5	2.1	ns
t_{RCKSW}	Maximum Skew (50% Load)	0.9	1.0	1.2	1.4	1.9	ns
t_{RCKSW}	Maximum Skew (100% Load)	0.9	1.0	1.2	1.4	1.9	ns

Note: *All -3 speed grades have been discontinued.

Table 2-31 • A54SX32A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 4.75\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.7	1.9	2.2	2.6	4.0	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.7	2.0	2.2	2.6	4.0	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{HCKSW}	Maximum Skew	0.6	0.6	0.7	0.8	1.3	ns
t_{HP}	Minimum Period	2.8	3.2	3.6	4.2	5.8	ns
f_{HMAX}	Maximum Frequency	357	313	278	238	172	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	2.2	2.5	2.8	3.3	4.7	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	2.1	2.5	2.8	3.3	4.5	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	2.4	2.7	3.1	3.6	5.1	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	2.2	2.6	2.9	3.4	4.7	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	2.5	2.8	3.2	3.8	5.3	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	2.4	2.8	3.1	3.7	5.2	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{RCKSW}	Maximum Skew (Light Load)	1.0	1.1	1.3	1.5	2.1	ns
t_{RCKSW}	Maximum Skew (50% Load)	1.0	1.1	1.3	1.5	2.1	ns
t_{RCKSW}	Maximum Skew (100% Load)	1.0	1.1	1.3	1.5	2.1	ns

Note: *All -3 speed grades have been discontinued.

Table 2-35 • A54SX72A Timing Characteristics
 (Worst-Case Commercial Conditions, $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹		-2 Speed		-1 Speed		Std. Speed	-F Speed	Units	
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
C-Cell Propagation Delays²											
t_{PD}	Internal Array Module	1.0		1.1		1.3		1.5		2.0	ns
Predicted Routing Delays³											
t_{DC}	FO = 1 Routing Delay, Direct Connect	0.1		0.1		0.1		0.1		ns	
t_{FC}	FO = 1 Routing Delay, Fast Connect	0.3		0.3		0.3		0.4		0.6	ns
t_{RD1}	FO = 1 Routing Delay	0.3		0.3		0.4		0.5		0.7	ns
t_{RD2}	FO = 2 Routing Delay	0.4		0.5		0.6		0.7		1	ns
t_{RD3}	FO = 3 Routing Delay	0.5		0.7		0.8		0.9		1.3	ns
t_{RD4}	FO = 4 Routing Delay	0.7		0.9		1		1.1		1.5	ns
t_{RD8}	FO = 8 Routing Delay	1.2		1.5		1.7		2.1		2.9	ns
t_{RD12}	FO = 12 Routing Delay	1.7		2.2		2.5		3		4.2	ns
R-Cell Timing											
t_{RCO}	Sequential Clock-to-Q	0.7		0.8		0.9		1.1		1.5	ns
t_{CLR}	Asynchronous Clear-to-Q	0.6		0.7		0.7		0.9		1.2	ns
t_{PRESET}	Asynchronous Preset-to-Q	0.7		0.8		0.8		1.0		1.4	ns
t_{SUD}	Flip-Flop Data Input Set-Up	0.7		0.8		0.9		1.0		1.4	ns
t_{HD}	Flip-Flop Data Input Hold	0.0		0.0		0.0		0.0		0.0	ns
t_{WASYN}	Asynchronous Pulse Width	1.3		1.5		1.7		2.0		2.8	ns
$t_{RECASYN}$	Asynchronous Recovery Time	0.3		0.4		0.4		0.5		0.7	ns
t_{HASYN}	Asynchronous Hold Time	0.3		0.3		0.3		0.4		0.6	ns
t_{MPW}	Clock Minimum Pulse Width	1.5		1.7		2.0		2.3		3.2	ns
Input Module Propagation Delays											
t_{INYH}	Input Data Pad to Y High 2.5 V LVC MOS	0.6		0.7		0.8		0.9		1.3	ns
t_{INYL}	Input Data Pad to Y Low 2.5 V LVC MOS	0.8		1.0		1.1		1.3		1.7	ns
t_{INYH}	Input Data Pad to Y High 3.3 V PCI	0.6		0.7		0.7		0.9		1.2	ns
t_{INYL}	Input Data Pad to Y Low 3.3 V PCI	0.7		0.8		0.9		1.0		1.4	ns
t_{INYH}	Input Data Pad to Y High 3.3 V LV TTL	0.7		0.7		0.8		1.0		1.4	ns
t_{INYL}	Input Data Pad to Y Low 3.3 V LV TTL	1.0		1.2		1.3		1.5		2.1	ns

Notes:

1. All -3 speed grades have been discontinued.
2. For dual-module macros, use $t_{PD} + t_{RD1} + t_{PDn}$, $t_{RCO} + t_{RD1} + t_{PDn}$, or $t_{PD1} + t_{RD1} + t_{SUD}$, whichever is appropriate.
3. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual performance.

Table 2-39 • A54SX72A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 2.3\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
2.5 V LVC MOS Output Module Timing^{2, 3}							
t_{DLH}	Data-to-Pad Low to High	3.9	4.5	5.1	6.0	8.4	ns
t_{DHL}	Data-to-Pad High to Low	3.1	3.6	4.1	4.8	6.7	ns
t_{DHLS}	Data-to-Pad High to Low—low slew	12.7	14.6	16.5	19.4	27.2	ns
t_{ENZL}	Enable-to-Pad, Z to L	2.4	2.8	3.2	3.7	5.2	ns
t_{ENZLS}	Data-to-Pad, Z to L—low slew	11.8	13.7	15.5	18.2	25.5	ns
t_{ENZH}	Enable-to-Pad, Z to H	3.9	4.5	5.1	6.0	8.4	ns
t_{ENLZ}	Enable-to-Pad, L to Z	2.1	2.5	2.8	3.3	4.7	ns
t_{ENHZ}	Enable-to-Pad, H to Z	3.1	3.6	4.1	4.8	6.7	ns
d_{TLH}^4	Delta Low to High	0.031	0.037	0.043	0.051	0.071	ns/pF
d_{THL}^4	Delta High to Low	0.017	0.017	0.023	0.023	0.037	ns/pF
d_{THLS}^4	Delta High to Low—low slew	0.057	0.06	0.071	0.086	0.117	ns/pF

Note:

1. All -3 speed grades have been discontinued.
2. Delays based on 35 pF loading.
3. The equivalent IO Attribute settings for 2.5 V LVC MOS is 2.5 V LVTTL in the software.
4. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[LH|HL|HLS]})$$
 where C_{load} is the load capacitance driven by the I/O in pF
 $d_{T[LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.

Table 2-41 • A54SX72A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 4.75\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
5 V PCI Output Module Timing²							
t_{DLH}	Data-to-Pad Low to High	2.7	3.1	3.5	4.1	5.7	ns
t_{DHL}	Data-to-Pad High to Low	3.4	3.9	4.4	5.1	7.2	ns
t_{ENZL}	Enable-to-Pad, Z to L	1.3	1.5	1.7	2.0	2.8	ns
t_{ENZH}	Enable-to-Pad, Z to H	2.7	3.1	3.5	4.1	5.7	ns
t_{ENLZ}	Enable-to-Pad, L to Z	3.0	3.5	3.9	4.6	6.4	ns
t_{ENHZ}	Enable-to-Pad, H to Z	3.4	3.9	4.4	5.1	7.2	ns
d_{TLH}^3	Delta Low to High	0.016	0.016	0.02	0.022	0.032	ns/pF
d_{THL}^3	Delta High to Low	0.026	0.03	0.032	0.04	0.052	ns/pF
5 V TTL Output Module Timing⁴							
t_{DLH}	Data-to-Pad Low to High	2.4	2.8	3.1	3.7	5.1	ns
t_{DHL}	Data-to-Pad High to Low	3.1	3.5	4.0	4.7	6.6	ns
t_{DHLS}	Data-to-Pad High to Low—low slew	7.4	8.5	9.7	11.4	15.9	ns
t_{ENZL}	Enable-to-Pad, Z to L	2.1	2.4	2.7	3.2	4.5	ns
t_{ENZLS}	Enable-to-Pad, Z to L—low slew	7.4	8.4	9.5	11.0	15.4	ns
t_{ENZH}	Enable-to-Pad, Z to H	2.4	2.8	3.1	3.7	5.1	ns
t_{ENLZ}	Enable-to-Pad, L to Z	3.6	4.2	4.7	5.6	7.8	ns
t_{ENHZ}	Enable-to-Pad, H to Z	3.1	3.5	4.0	4.7	6.6	ns
d_{TLH}^3	Delta Low to High	0.014	0.017	0.017	0.023	0.031	ns/pF
d_{THL}^3	Delta High to Low	0.023	0.029	0.031	0.037	0.051	ns/pF
d_{THLS}^3	Delta High to Low—low slew	0.043	0.046	0.057	0.066	0.089	ns/pF

Notes:

1. All -3 speed grades have been discontinued.
2. Delays based on 50 pF loading.
3. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[LH|HL|HLS]})$$

where C_{load} is the load capacitance driven by the I/O in pF

$d_{T[LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.
4. Delays based on 35 pF loading.

329-Pin PBGA	
Pin Number	A54SX32A Function
V22	I/O
V23	I/O
W1	I/O
W2	I/O
W3	I/O
W4	I/O
W20	I/O
W21	I/O
W22	I/O
W23	NC
Y1	NC
Y2	I/O
Y3	I/O
Y4	GND
Y5	I/O
Y6	I/O
Y7	I/O
Y8	I/O
Y9	I/O
Y10	I/O
Y11	I/O
Y12	V _{CCA}
Y13	NC
Y14	I/O
Y15	I/O
Y16	I/O
Y17	I/O
Y18	I/O
Y19	I/O
Y20	GND
Y21	I/O
Y22	I/O
Y23	I/O

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
E11	I/O	I/O	I/O
E12	I/O	I/O	I/O
E13	NC	I/O	I/O
E14	I/O	I/O	I/O
E15	I/O	I/O	I/O
E16	I/O	I/O	I/O
F1	I/O	I/O	I/O
F2	I/O	I/O	I/O
F3	I/O	I/O	I/O
F4	TMS	TMS	TMS
F5	I/O	I/O	I/O
F6	I/O	I/O	I/O
F7	V _{CCI}	V _{CCI}	V _{CCI}
F8	V _{CCI}	V _{CCI}	V _{CCI}
F9	V _{CCI}	V _{CCI}	V _{CCI}
F10	V _{CCI}	V _{CCI}	V _{CCI}
F11	I/O	I/O	I/O
F12	VCCA	VCCA	VCCA
F13	I/O	I/O	I/O
F14	I/O	I/O	I/O
F15	I/O	I/O	I/O
F16	I/O	I/O	I/O
G1	NC	I/O	I/O
G2	I/O	I/O	I/O
G3	NC	I/O	I/O
G4	I/O	I/O	I/O
G5	I/O	I/O	I/O
G6	V _{CCI}	V _{CCI}	V _{CCI}
G7	GND	GND	GND
G8	GND	GND	GND
G9	GND	GND	GND
G10	GND	GND	GND
G11	V _{CCI}	V _{CCI}	V _{CCI}
G12	I/O	I/O	I/O
G13	GND	GND	GND
G14	NC	I/O	I/O
G15	V _{CCA}	V _{CCA}	V _{CCA}

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
G16	I/O	I/O	I/O
H1	I/O	I/O	I/O
H2	I/O	I/O	I/O
H3	V _{CCA}	V _{CCA}	V _{CCA}
H4	TRST, I/O	TRST, I/O	TRST, I/O
H5	I/O	I/O	I/O
H6	V _{CCI}	V _{CCI}	V _{CCI}
H7	GND	GND	GND
H8	GND	GND	GND
H9	GND	GND	GND
H10	GND	GND	GND
H11	V _{CCI}	V _{CCI}	V _{CCI}
H12	I/O	I/O	I/O
H13	I/O	I/O	I/O
H14	I/O	I/O	I/O
H15	I/O	I/O	I/O
H16	NC	I/O	I/O
J1	NC	I/O	I/O
J2	NC	I/O	I/O
J3	NC	I/O	I/O
J4	I/O	I/O	I/O
J5	I/O	I/O	I/O
J6	V _{CCI}	V _{CCI}	V _{CCI}
J7	GND	GND	GND
J8	GND	GND	GND
J9	GND	GND	GND
J10	GND	GND	GND
J11	V _{CCI}	V _{CCI}	V _{CCI}
J12	I/O	I/O	I/O
J13	I/O	I/O	I/O
J14	I/O	I/O	I/O
J15	I/O	I/O	I/O
J16	I/O	I/O	I/O
K1	I/O	I/O	I/O
K2	I/O	I/O	I/O
K3	NC	I/O	I/O
K4	V _{CCA}	V _{CCA}	V _{CCA}